



Material Content Data Sheet



Sales Product Name		TLE75008-ESD		Issued		22. January 2018			
MA#		MA001682904							
Package		PG-TSDSO-24-21		Weight*		796.54 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.881	0.24	0.24	2361	2361	
leadframe	inorganic material	phosphorus	7723-14-0	0.064	0.01		80		
		non noble metal	zinc	7440-66-6	0.256	0.03		321	
		non noble metal	iron	7439-89-6	5.116	0.64		6423	
wire	non noble metal	non noble metal	copper	7440-50-8	207.751	26.08	26.76	260818	267642
		non noble metal	copper	7440-50-8	0.864	0.11	0.11	1084	1084
		encapsulation	organic material	carbon black	1333-86-4	1.727	0.22		2169
encapsulation	plastics	epoxy resin	-	67.369	8.46		84578		
		inorganic material	silicondioxide	60676-86-0	506.708	63.61	72.29	636138	722885
leadfinish	non noble metal	tin	7440-31-5	3.642	0.46	0.46	4573	4573	
plating	noble metal	silver	7440-22-4	0.339	0.04	0.04	426	426	
glue	plastics	epoxy resin	-	0.143	0.02		180		
		noble metal	silver	7440-22-4	0.676	0.08	0.10	849	1029
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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